

4- Point Chuck

mV- Chuck Series



Features

- available for different wafer sizes (6"/8"/12")
- special designed for MEMS- glass wafer
- controlled vacuum flow

ASK FOR YOUR CUSTOMIZED SOLUTION!

Functional description

mechatronic vacuum chucks (mVC) are designed for secure placement of various wafer types (eg. standard, (ultra-)thin/warped, eWLB, Taiko, film-frame, MEMS) in a defined orientation. These chucks are mainly integrated in OEM-equipment (eg. for inspection measurement, defect detection, ...) under atmospheric conditions.

4-point chucks are designed to hold the wafer with most limited vacuum support in the exclusion area only (eg. safe MEMS wafer handling). Taking advantage of low surface contact the wafer will be accessible from both sides for further processing, eliminating wafer stress or risk of particle transfer/generation.

Loading	Automated or manual from top side
Wafer detection	Vacuum
Centering accuracy (X, Y axis)	n.a.
Suitable End- effector	Top Grip End- effector, Contactless End- effector, Needle End- effector
Materials	Stainless steel, anodized aluminum, PEEK, NBR;
Pneumatic	
Pneumatic media	Vacuum
Supply Vacuum	-85 kPa

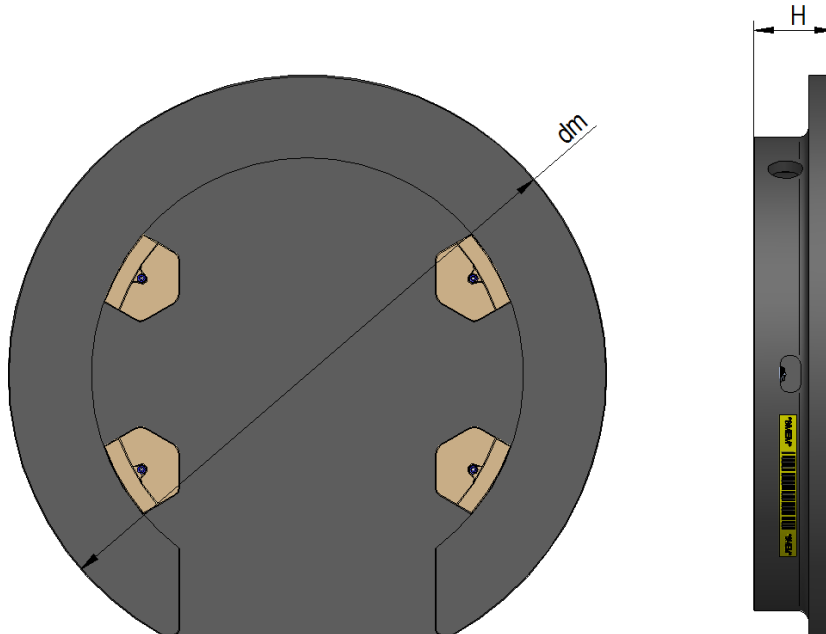
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4- Point Chuck

mV- Chuck Types & sizes

Type	mV- Chuck 150	mV- Chuck 200	mV- Chuck 300
Wafer size	150 mm (6")	200 mm (8")	300 mm (12")
Wafer thickness	> 200 µm (7,8 mils)	> 200 µm (7,8 mils)	n.a.
Warpage (depends on wafer thickness)	Up to 200 µm	Up to 200 µm	n.a.
Weight	2600 g	2650 g	n.a.
Mechanical dimensions in mm			
dm (diameter)	305 mm	305 mm	n.a.
D (height)	40 mm	40 mm	n.a.

Special customized designs available!



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